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# 11/15/2006 RFEKADUI 00000082 10725933

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

THE APPLICATION OF

Yang et al.

**FOR** 

: FAN OUT TYPE WAFER LEVEL PACKAGE

STRUCTURE AND METHOD OF THE SAME

SERIAL NO.

10/725,933

**FILED** 

December 3, 2003

CONFIRMATION NO.

4487

**EXAMINER** 

David A. Zarneke

**ART UNIT** 

2891

ATTORNEY DOCKET NO.

HK9225US (formerly 25857)

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

### INFORMATION DISCLOSURE STATEMENT

Sir:

1. Pursuant to 37 C.F.R. 1.97 and 1.98, and in compliance with 37 C.F.R. 1.56, the Office's attention is directed to the patents, publications and other information listed on the attached form PTO-1449. The required copy of each document is enclosed *except for* documents previously cited by or submitted to the Office in a prior application(s) relied upon for an earlier filing date under 35 U.S.C. 120, said prior application(s) identified below:

### Serial No.

### Filing Date

- 2. Pursuant to 37 C.F.R. 1.97(g), the filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made.
- 3. Pursuant to 37 C.F.R. 1.97(h), the filing of this Information Disclosure Statement shall not be construed as an admission that the information cited in this Statement is, or is considered to be, material to patentability as defined in 37 C.F.R. 1.56(b).
- 4. Regarding each listed document that is not in the English language, an English-language translation accompanies this Statement as indicated on the attached PTO-1449 or a concise explanation of the relevance of the document is set forth in the following document(s):
  - () Copy of each English language version of a search report by a foreign patent office in a counterpart foreign application, indicating the degree of relevance found by the foreign office of each document being submitted from the search report.

- () Attachment entitled "Concise Explanation of Relevance of Non-English Language Documents."
- () English-language abstract.

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- () 5. Pursuant to 37 C.F.R. 1.97(b) this Statement is being filed:
  - () concurrently with the filing of the national application; or
  - () within 3 months of the filing date of a national application or
  - () within 3 months of the date of the entry of the national stage as set forth in 37 CFR 1.491 in an international application; or
  - () before the mailing date of a first Office Action on the merits.

{NOTE: Statements filed within the foregoing periods require neither a fee nor a Certification}

- (X) 6. Pursuant to 37 C.F.R. 1.97(c) this Statement is being filed *after* the mailing date of a first Office Action on the merits but *before* the mailing date of either: a Final Office Action under 37 C.F.R. 1.113 or a Notice of Allowance under 37 C.F.R. 1.311, whichever occurs first. Accordingly, this Statement is accompanied by:
  - () Certification as specified in 37 C.F.R. 1.97(e); OR
  - (X)The submission fee set forth in 37 C.F.R. 1.17(p). Enclosed is Form PTO-2038 authorizing the amount of \$180 to be charged to our credit card to cover the fee set forth in 37 C.F.R. 1.17(p) for consideration of this Statement.
- () 7. Pursuant to 37 C.F.R. 1.97(d) this Statement is being filed *after* the period specified in 37 C.F.R. 1.97(c), but *before or concurrent with* payment of the Issue Fee. Accordingly, this Statement is accompanied by:
  - A. Certification as specified in 37 C.F.R. 1.97(e); AND
  - B. The submission fee set forth in 37 C.F.R. 1.17(p). Enclosed is Form PTO-2038 authorizing the amount of \$180 to be charged to our credit card to cover the fee set forth in 37 C.F.R. 1.17(p) for consideration of this Statement.
- () 8. Statement filed after payment of Issue Fee, but before patent grant:

This Statement is being filed *after* payment of the Issue Fee, but *before* grant of the patent; accordingly it is understood that this Statement will *not* be considered. However, it is respectfully requested that this Information Disclosure Statement be placed in the application file. {NOTE: No fees or certification required}

- () 9. CERTIFICATION under 37 C.F.R. 1.97 (e) (if applicable):
  - () The undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than 3 monthsprior to the filing of this Information Disclosure Statement, **OR**
  - () The undersigned hereby certifies that no item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned, after making reasonable inquiry, no item of information contained in this Information Disclosure Statement was known to any individual designated in 37 C.F.R. 1.56(c) more than 3 months prior to the filing of this Information Disclosure Statement.

The Commissioner is hereby authorized to charge any additional fees required for consideration of this Information Disclosure Statement, or credit any overpayment to Deposit Account No. 50-0537, identifying our Docket No. HK9225US.

Date: November 9, 2006

Respectfully submitted,

Michael A. Jaffe // V Registration No. 36,326

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Lawal Cabiel

# **CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8**

I hereby certify that this correspondence (along with any paper referenced as being attached or enclosed) is being deposited on the below date with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: November 9, 2006



U.S. Application No.: 10/725,933

Attorney Docket No.: HK9225US (formerly 25857)

IDS Filed: November 9, 2006

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

# **INFORMATION DISCLOSURE CITATION**

In re application of: Yang et al.

Confirmation No.: 4487

Serial No.: 10/725,933

Group No.: 2891

Filed: December 3, 2003

Examiner: David A. Zarneke

FAN OUT TYPE WAFER LEVEL PACKAGE STRUCTURE AND METHOD OF THE SAME For:

Mail Stop Amendment Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

## **Foreign Patent Documents**

Examiner <u>Initials</u>	Document Number	Country	Date of Publication	Class	Translation (Yes/No)
	177,766	Taiwan	09/05/2003	H01L23/02	Yes
<del></del>	Abstract of Taiwan Patent Publication No. TW 531854B, published 05/11/2003.				
Examiner:			Date (	Considered:	
Examiner:			Date	considerea:	
			`		<del>_</del>

\*\*Examiner:

Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.